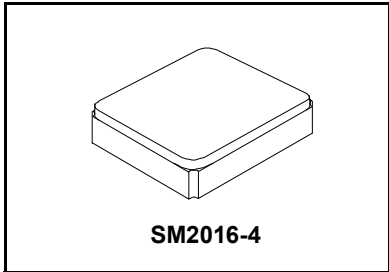


- *Designed for Front End GPS, Beidou, and Glonass Applications*
- *Steep Rejection*
- *2.0 x 1.6 x 1.0 mm Surface-Mount Case*
- *Complies with Directive 2002/95/EC (RoHS)*
- *AEC-Q200 Qualified*

RoHS
Compliant

SF2467H

1542 MHz
SAW Filter



Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+20	dBm
DC Voltage	5	VDC
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +105	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Moisture Sensitivity Level	Level 1 (MSL1)	

Electrical Characteristics

Characteristic	Sym	NOTE	-40 to +105°C			UNITS
			MIN	TYPICAL	MAX	
Center Frequency	F _c			1542		MHz
Insertion Loss, 1525 to 1559 MHz	IL	3		2.5	3.3	dB
S11, 1525 to 1559 MHz			10			
Group Delay Variation, 1525 to 1559 MHz				10	20	ns
Attenuation Referenced to 0 dB:						dB
100 to 1480 MHz			43	48		
1630 to 1660 MHz			38	43		
1660 to 2050 MHz			41	46		
2050 to 3500 MHz			35	40		
Temperature Coefficient of Frequency				-36		ppm/°C
Source impedance	Z _S			50		Ω
Load impedance	Z _L			50		Ω

Standard Reel Quantity	Reel Size: 7 inch	2000 Pieces/Reel
	Reel size: 13 inch	10,000 Pieces/Reel
Single-ended Input / Output Impedance Match	No matching network required for operation at 50 ohms	
Package Size	SM2016-4	
Lid Symbolization (Y=year, W=week)	B4, <u>YW</u>	



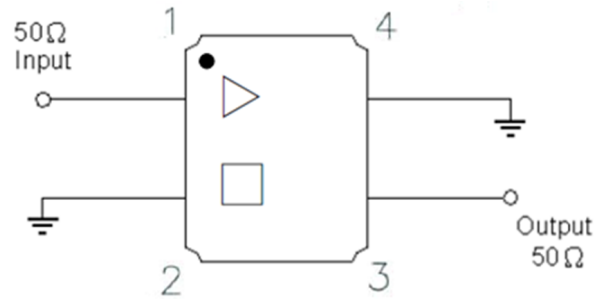
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

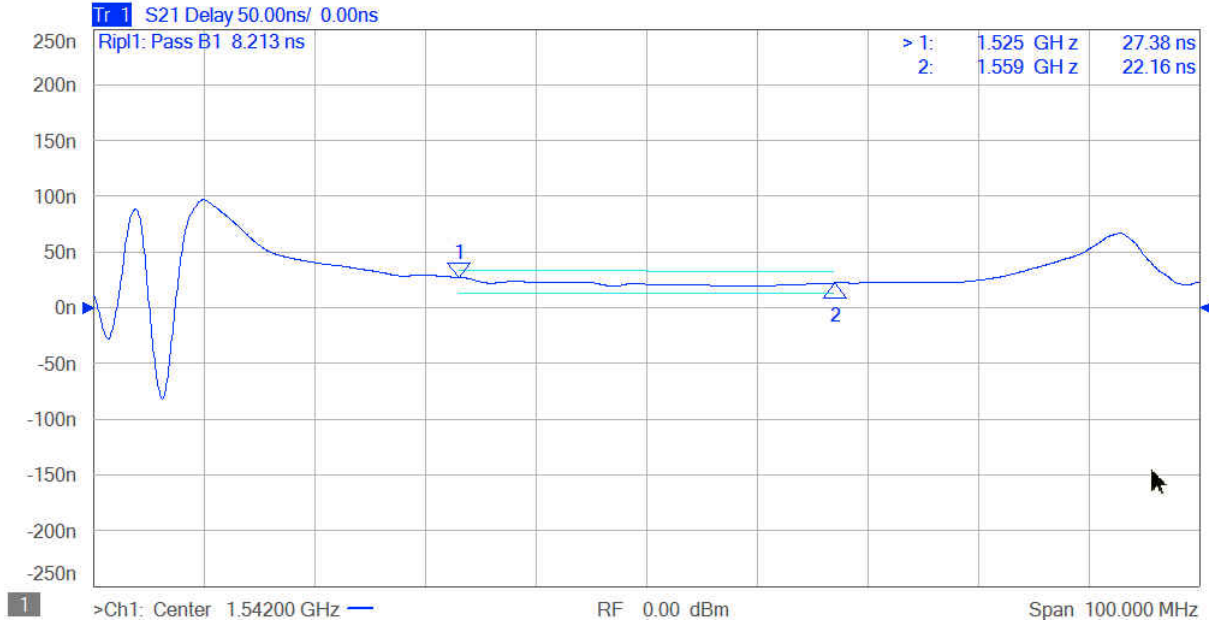
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. Maximum insertion loss = 3.0 dB @ 85°C

Electrical Connections

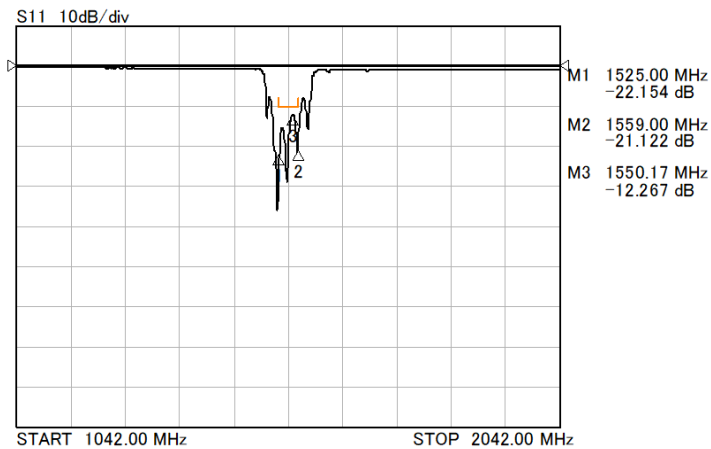
Connection	Terminals
Input	1
Output	3
Ground	All others



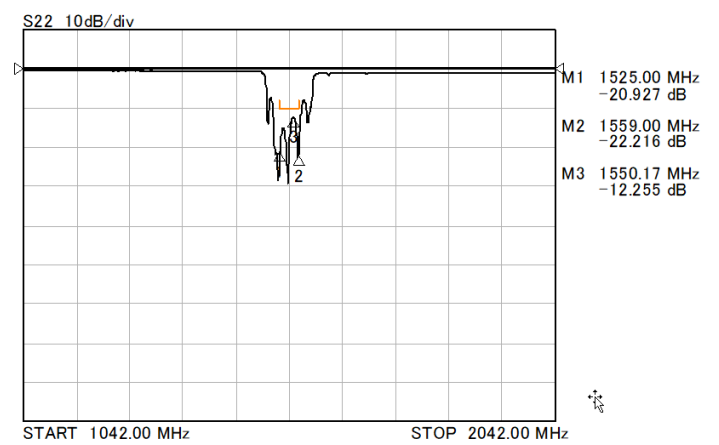
Frequency Characteristics



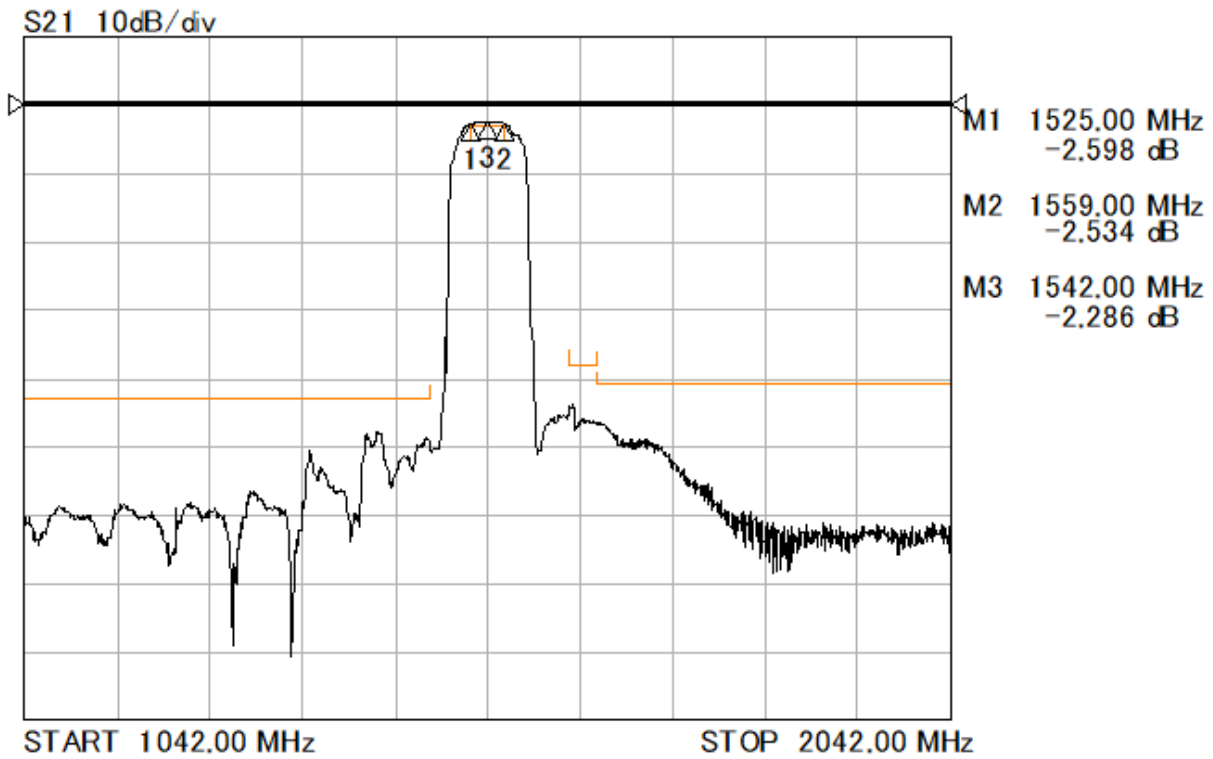
S11 Response



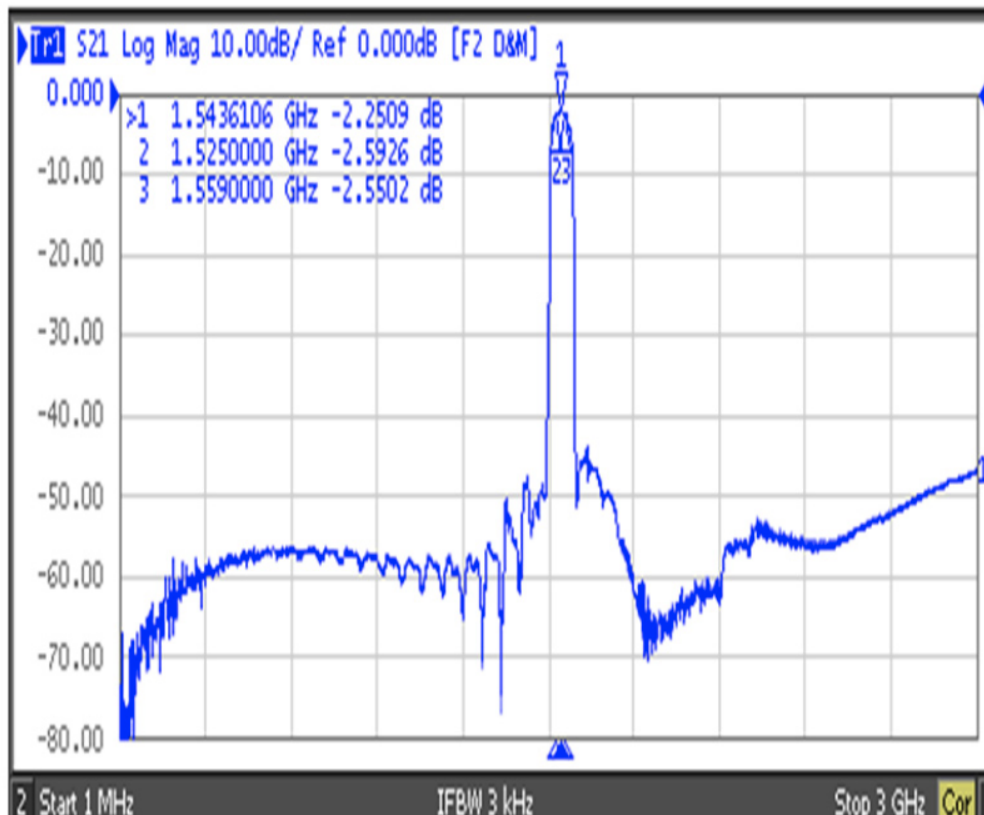
S22 Response



S21 Response: (span 1 GHz)



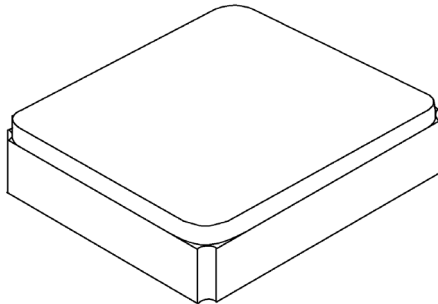
S21 Response: (span 3 GHz)



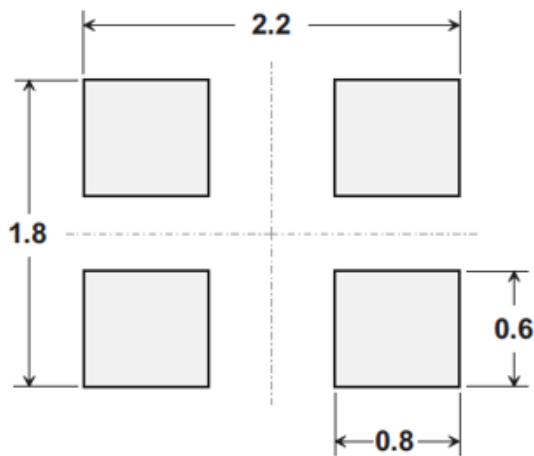
SM2016-4 Case

4-Terminal Ceramic Surface-Mount Case

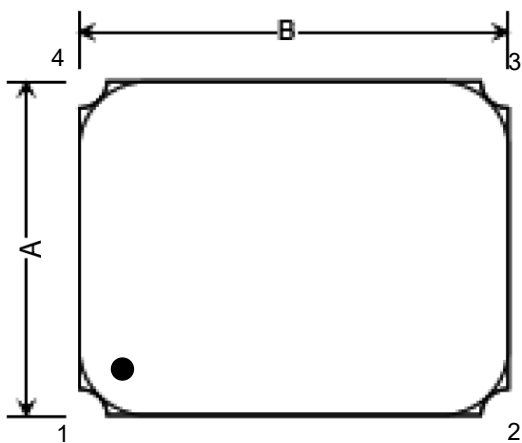
2.0 X 1.6 mm Nominal Footprint



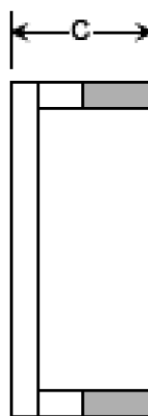
PCB Pad Layout



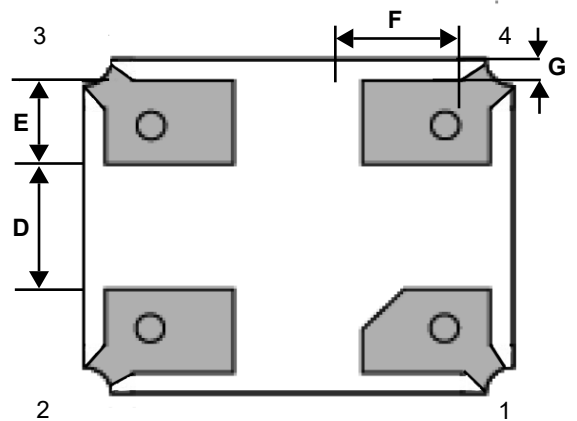
Dimensions are in mm
All pads have the same dimension



SIDE VIEW



BOTTOM VIEW



Case Dimensions

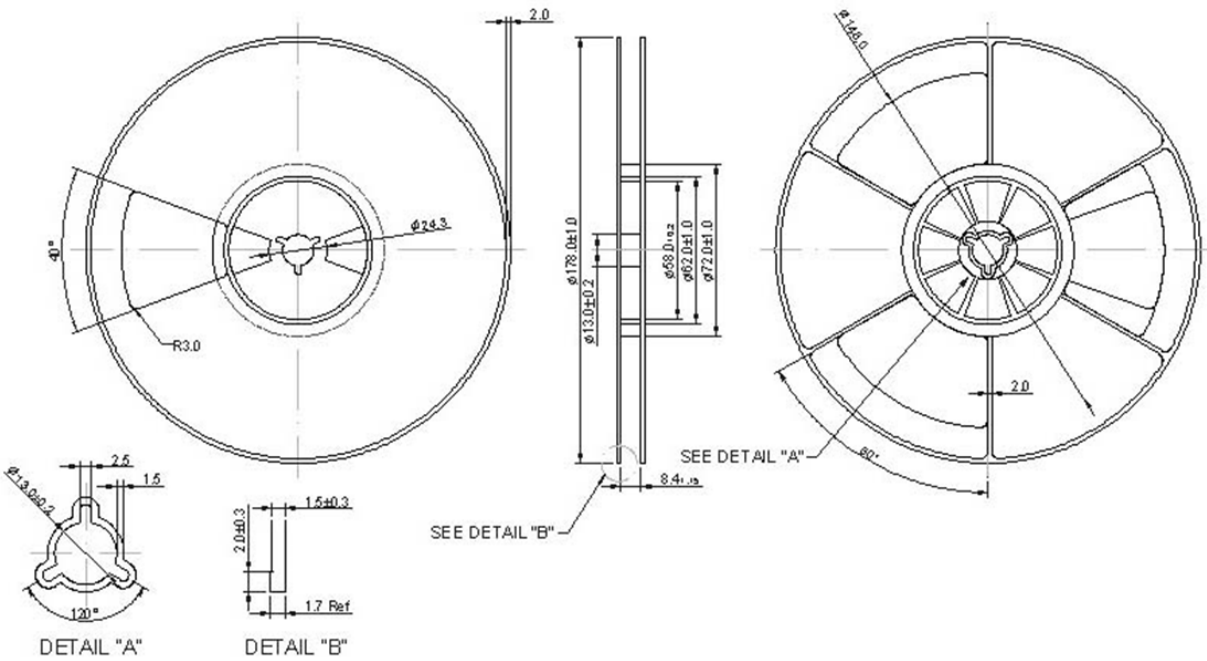
Dimension	mm		
	Min	Nom	Max
A	1.58	1.65	1.72
B	1.98	2.05	2.12
C	0.44	0.52	0.58
D		0.60	
E		0.425	
F		0.625	
G		0.10	

Materials

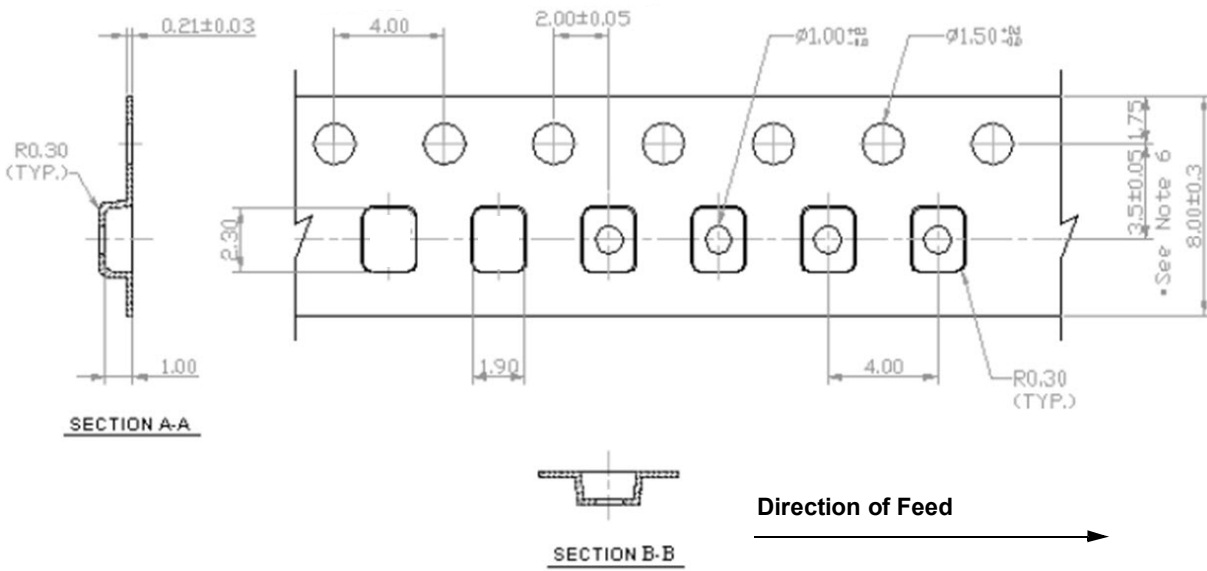
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

Tape and Reel Standard per ANSI/EIA-481

Reel Dimensions



Tape Dimensions



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

